



Patent Application No. 10/618,536
Customer Number: 42717

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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|--------------|-------------------------------|---|-------------|-----------------|
| Applicant: | Jing Cheng Lin, et al. | § | Docket No.: | 24061.485 |
| | | § | | (TSMC2002-0360) |
| Serial No.: | 10/618,536 | § | | |
| | | § | Examiner: | Thien F. Tran |
| Filing Date: | June 11, 2003 | § | | |
| | | § | Art Unit: | 2811 |
| For: | Adhesion Copper and Etch Stop | § | | |
| | Layer for Copper Alloy | § | Conf. No.: | 5026 |
| | | § | | |

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop: Amendment
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed August 20, 2004, applicant hereby elects, Group II, Claims 1-18 and 30-32, which is drawn to a process for making semiconductor devices.

Applicant's election is made with traverse on the grounds that the embodiments delineated by the examiner are not patentably distinct and therefore constitute a single invention concept.

An early action on the merits is respectfully requested.

Respectfully submitted,

David M. O'Dell
Reg. No. 42,044

Date: 10-20-04

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop: Amendment, Commissioner For Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date below.

Bonnie Boyce
Name

10-20-04
Date